

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT5190679

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ALEXANDER KALNITSKY	05/09/2018
SHENG-HUANG HUANG	05/08/2018
HARRY-HAK-LAY CHUANG	05/08/2018
JIUNYU TSAI	05/08/2018
HUNG CHO WANG	05/08/2018
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LTD.
Street Address:	NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15961157
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SIGNATURE:	/Anthony King/
DATE SIGNED:	10/16/2018
Total Attachments: 2	
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source=US7067_Assignment#page2.tif	

ASSIGNMENT

WHEREAS, I(we), KALNITSKY, ALEXANDER, HUANG, SHENG-HUANG, CHUANG, HARRY-HAK-LAY, TSAL JIUNYU and WANG, HUNG CHO whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented certain new and useful invention entitled

SEMICONDUCTOR STRUCTURE AND MANUFACTURING METHOD OF THE SAME

(hereinafter referred to as the INVENTION) for which an application for United States Letters Patent /Utility Patent is executed on even date herewith unless at least one of the following is checked:

- ☐ United States Design Patent was
☐ executed on:
☒ filed on: 24 April 2018 Serial No.: 15/961,157
☐ established by PCT International Patent Application No.: filed: designating the
United States of America
☐ issued on _____ as U.S. Patent No.: _____

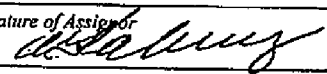
WHEREAS, TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LTD. whose post office address is NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK, HSINCHU, TAIWAN, R.O.C. hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States and its territorial possessions;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application for the full term or terms for which the same may be granted, including all priority rights under any International Convention.

ASSIGNOR further covenants that no assignments, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment;

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) in the United States for said INVENTION, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said INVENTION, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE's expense, to identify and communicate to ASSIGNEE at ASSIGNEE's request documents and information concerning the INVENTION that are within ASSIGNOR'S possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance, litigation and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR'S obligations under this instrument shall extend to ASSIGNOR'S heirs, executors, administrators and other legal representatives.

ALSO, ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE'S sole use and behoof; and for the use and behoof of ASSIGNEE'S legal representatives and successors, to the full end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

Assignor Name KALNITSKY, ALEXANDER	Address 737 LA PLAYA #B, SAN FRANCISCO, CA 94121, U.S.A.
Signature of Assignor (X) 	Date of Signature (X) 5/9/2018
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

Assignor Name HUANG, SHENG-HUANG	Address NO. 139, LN. 420, SEC. 5, ZHONGHUA RD., XIANGSHAN DIST., HSINCHU CITY 300, TAIWAN (R.O.C.)
Signature of Assignor (X) <i>Huang, Sheng-huang</i>	Date of Signature (X) 2018.05.08
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

Assignor Name CHUANG, HARRY-HAK-LAY	Address 51 PAYA LEBAR CRESCENT, SINGAPORE 536191
Signature of Assignor (X) <i>Chuang, Harry-Hak-Lay</i>	Date of Signature (X) 5/8/2018
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

Assignor Name TSAI, JIUNYU	Address NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK, HSINCHU, TAIWAN (R.O.C.)
Signature of Assignor (X) <i>Tsai, JunYu</i>	Date of Signature (X) 2018.05.08
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

Assignor Name WANG, HUNG CHO	Address 7F NO.190 WANDA RD., TAIPEI, TAIWAN (R.O.C.)
Signature of Assignor (X) <i>Wang, Hung Cho</i>	Date of Signature (X) 2018.5.8
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)